4 M SRAM (512-kword \times 8-bit)

HITACHI

ADE-203-1212B (Z) Rev. 2.0 May. 14, 2001

Description

The Hitachi HM628512C is a 4-Mbit static RAM organized 512-kword \times 8-bit. It realizes higher density, higher performance and low power consumption by employing CMOS process technology (6-transistor memory cell). The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II or 600-mil plastic DIP, is available for high density mounting. The HM628512C is suitable for battery backup system.

Features

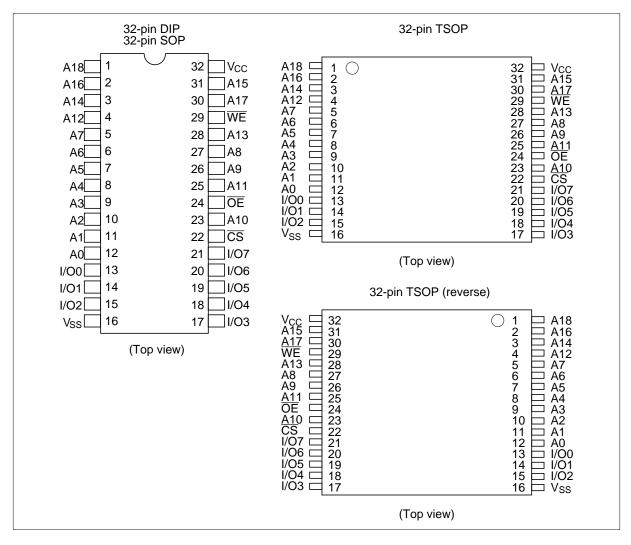
- Single 5 V supply
- Access time: 55/70 ns (max)
- Power dissipation
 - Active: 10 mW/MHz (typ)
 - Standby: 4 µW (typ)
- Completely static memory. No clock or timing strobe required
- Equal access and cycle times
- Common data input and output: Three state output
- Directly TTL compatible: All inputs and outputs
- Battery backup operation



Ordering Information

Type No.	Access time	Package
HM628512CLP-5 HM628512CLP-7	55 ns 70 ns	600-mil 32-pin plastic DIP (DP-32)
HM628512CLP-5SL	55 ns	_
HM628512CLFP-5 HM628512CLFP-7	55 ns 70 ns	525-mil 32-pin plastic SOP (FP-32D)
HM628512CLFP-5SL	55 ns	_
HM628512CLTT-5 HM628512CLTT-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II (TTP-32D)
HM628512CLTT-5SL	55 ns	_
HM628512CLRR-5 HM628512CLRR-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II reverse (TTP-32DR)
HM628512CLRR-5SL	55 ns	_

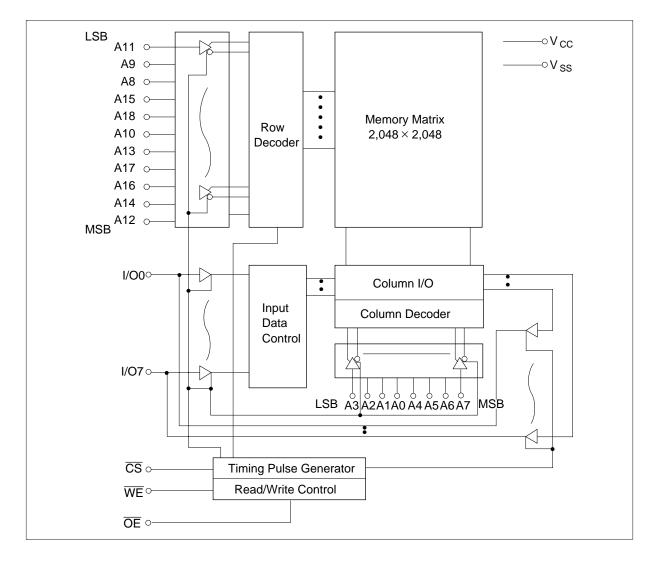
Pin Arrangement



Pin Description

Pin name	Function
A0 to A18	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
ŌĒ	Output enable
WE	Write enable
V _{cc}	Power supply
V _{ss}	Ground

Block Diagram



Function Table

WE	CS	OE	Mode	V _{cc} current	Dout pin	Ref. cycle
×	Н	×	Not selected	$ _{_{\rm SB}}, _{_{\rm SB1}}$	High-Z	—
Н	L	Н	Output disable	I _{cc}	High-Z	_
Н	L	L	Read	I _{cc}	Dout	Read cycle
L	L	Н	Write	I _{cc}	Din	Write cycle (1)
L	L	L	Write	I _{cc}	Din	Write cycle (2)

Note: X: H or L

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage	V _{cc}	–0.5 to +7.0	V
Voltage on any pin relative to V_{ss}	V _T	-0.5^{*1} to V _{cc} + 0.3 ^{*2}	V
Power dissipation	P _T	1.0	W
Operating temperature	Topr	-20 to +70	°C
Storage temperature	Tstg	-55 to +125	°C
Storage temperature under bias	Tbias	-20 to +85	°C

Notes: 1. V_{τ} min: -3.0 V for pulse half-width \leq 30 ns.

2. Maximum voltage is 7.0 V.

Recommended DC Operating Conditions (Ta = -20 to $+70^{\circ}$ C)

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{cc}	4.5	5.0	5.5	V
	V _{ss}	0	0	0	V
Input high voltage	V _{IH}	2.2	_	V _{cc} + 0.3	V
Input low voltage	V _{IL}	-0.3*1		0.8	V

Note: 1. V_{IL} min: -3.0 V for pulse half-width \leq 30 ns.

DC Characteristics

Parameter		Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leakage current		I _{LI}	_	_	1	μA	Vin = V_{ss} to V_{cc}
Output leakage curren	t	_{lo}		_	1	μA	$\overline{\frac{CS}{WE}} = V_{IH} \text{ or } \overline{OE} = V_{IH} \text{ or}$ $\overline{WE} = V_{IL}, V_{I/O} = V_{SS} \text{ to } V_{CC}$
Operating power supp	ly current: DC	I _{cc}		1.5	3	mA	$\overline{CS} = V_{IL},$ others = V_{IH}/V_{IL} , $I_{I/O} = 0$ mA
Operating power supply current	HM628512C-5	I _{CC1}	—	8	25	mA	$\label{eq:linear} \begin{array}{l} \mbox{Min cycle, duty} = 100\% \\ \hline \mbox{CS} = V_{\rm IL}, \mbox{others} = V_{\rm IH}/V_{\rm IL} \\ I_{\rm I/O} = 0 \mbox{ mA} \end{array}$
	HM628512C-7	I _{CC1}	_	7	25	mA	
Operating power supply current		I _{CC2}	—	2	5	mA	$\begin{array}{l} Cycle \ time = 1 \ \mu s, \\ duty = 100\% \\ I_{_{UO}} = 0 \ mA, \ \overline{CS} \leq 0.2 \ V \\ V_{_{IH}} \geq V_{_{CC}} - 0.2 \ V, \ V_{_{IL}} \leq 0.2 \ V \end{array}$
Standby power supply	current: DC	I _{SB}		0.1	0.5	mA	$\overline{\text{CS}} = \text{V}_{\text{IH}}$
Standby power supply current (1): DC		I _{SB1}		0.8*2	20* ²	μA	$Vin \ge 0 \text{ V}, \overline{CS} \ge V_{cc} - 0.2 \text{ V}$
			_	0.8*3	10* ³	μΑ	-
Output low voltage		V _{OL}			0.4	V	I _{oL} = 2.1 mA
Output high voltage		V _{OH}	2.4			V	I _{OH} = -1.0 mA

Notes: 1. Typical values are at V_{cc} = 5.0 V, Ta = +25°C and specified loading, and not guaranteed.

2. This characteristics is guaranteed only for L version.

3. This characteristics is guaranteed only for L-SL version.

Capacitance (Ta = $+25^{\circ}$ C, f = 1 MHz)

Parameter	Symbol	Тур	Max	Unit	Test conditions
Input capacitance*1	Cin	_	8	pF	Vin = 0 V
Input/output capacitance*1	C _{I/O}	_	10* ²	pF	$V_{I/O} = 0 V$

Notes: 1. This parameter is sampled and not 100% tested.

2. $C_{I/O}$ max = 12 pF only for HM628512CLP Series.

AC Characteristics (Ta = -20 to $+70^{\circ}$ C, V_{CC} = 5 V ± 10%, unless otherwise noted.)

Test Conditions

- Input pulse levels: 0.8 V to 2.4 V
- Input rise and fall time: 5 ns
- Input and output timing reference levels: 1.5 V
- Output load: 1 TTL Gate + C_L (100 pF) (HM628512C-7)
 - 1 TTL Gate + C_L (50 pF) (HM628512C-5)

(Including scope & jig)

Read Cycle

		HM628	8512C				
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read cycle time	t _{RC}	55	_	70	_	ns	
Address access time	t _{AA}	—	55	—	70	ns	
Chip select access time	t _{co}		55		70	ns	
Output enable to output valid	t _{oe}	_	25	—	35	ns	
Chip selection to output in low-Z	t _{LZ}	10		10		ns	2
Output enable to output in low-Z	t _{oLZ}	5		5		ns	2
Chip deselection to output in high-Z	t _{HZ}	0	20	0	25	ns	1, 2
Output disable to output in high-Z	t _{oHz}	0	20	0	25	ns	1, 2
Output hold from address change	t _{он}	10		10	_	ns	

Write Cycle

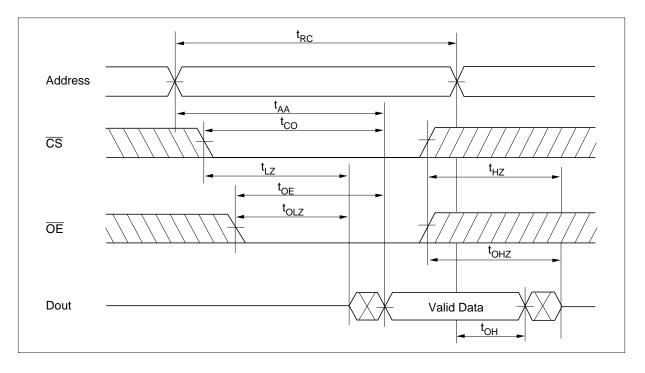
		HM62	8512C				
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write cycle time	t _{wc}	55		70		ns	
Chip selection to end of write	t _{cw}	50		60		ns	4
Address setup time	t _{AS}	0	_	0		ns	5
Address valid to end of write	t _{AW}	50		60		ns	
Write pulse width	t _{wP}	40		50		ns	3, 12
Write recovery time	t _{wR}	0	_	0	_	ns	6
WE to output in high-Z	t _{wHZ}	0	20	0	25	ns	1, 2, 7
Data to write time overlap	t _{DW}	25		30		ns	
Data hold from write time	t _{DH}	0	_	0	_	ns	
Output active from output in high-Z	t _{ow}	5		5		ns	2
Output disable to output in high-Z	t _{oHz}	0	20	0	25	ns	1, 2, 7

Notes: 1. t_{HZ}, t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

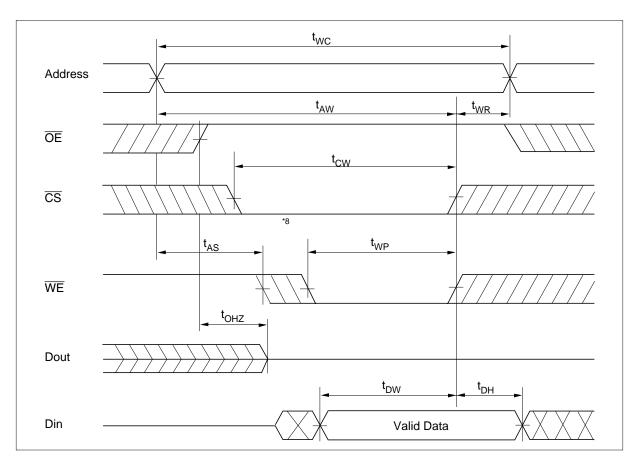
- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap (t_{WP}) of a low CS and a low WE. A write begins at the later transition of CS going low or WE going low. A write ends at the earlier transition of CS going high or WE going high. t_{WP} is measured from the beginning of write to the end of write.
- 4. t_{cw} is measured from \overline{CS} going low to the end of write.
- 5. t_{AS} is measured from the address valid to the beginning of write.
- 6. t_{WR} is measured from the earlier of \overline{WE} or \overline{CS} going high to the end of write cycle.
- 7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 8. If the CS low transition occurs simultaneously with the WE low transition or after the WE transition, the output remain in a high impedance state.
- 9. Dout is the same phase of the write data of this write cycle.
- 10. Dout is the read data of next address.
- 11. If CS is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
- 12. In the write cycle with \overline{OE} low fixed, t_{WP} must satisfy the following equation to avoid a problem of data bus contention. $t_{WP} \ge t_{DW}$ min + t_{WHZ} max

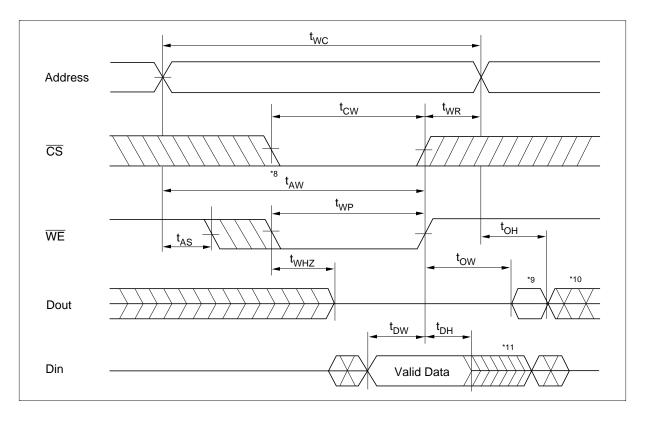
Timing Waveforms

Read Timing Waveform $(\overline{WE}=V_{\rm IH})$



Write Timing Waveform (1) $(\overline{OE} \operatorname{Clock})$





Write Timing Waveform (2) (OE Low Fixed)

Low V_{cc} Data Retention Characteristics (Ta = -20 to +70°C)

Parameter	Symbol	Min	Тур	Мах	Unit	Test conditions*3
V_{cc} for data retention	V_{DR}	2	_	_	V	$\overline{\text{CS}} \ge \text{V}_{\text{cc}} - 0.2 \text{ V}, \text{ Vin} \ge 0 \text{ V}$
Data retention current	I _{CCDR}	_	0.8*4	20*1	μΑ	$\frac{V_{cc}}{CS} = 3.0 \text{ V}, \text{ Vin} \ge 0 \text{ V}$ $\frac{V_{cc}}{CS} \ge V_{cc} - 0.2 \text{ V}$
		_	0.8*4	10* ²	μA	_
Chip deselect to data retention time	t _{CDR}	0	_	_	ns	See retention waveform
Operation recovery time	t _R	t _{RC} *5	_		ns	—

Notes: 1. For L-version and 10 μ A (max.) at Ta = -20 to +40°C.

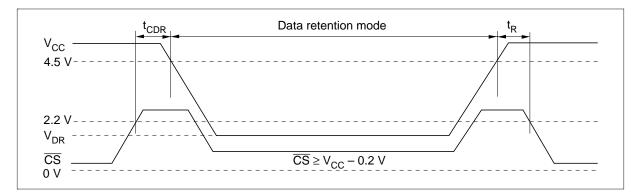
2. For L-SL-version and 3 μ A (max.) at Ta = -20 to +40°C.

3. CS controls address buffer, WE buffer, OE buffer, and Din buffer. In data retention mode, Vin levels (address, WE, OE, I/O) can be in the high impedance state.

4. Typical values are at V_{cc} = 3.0 V, Ta = +25°C and specified loading, and not guaranteed.

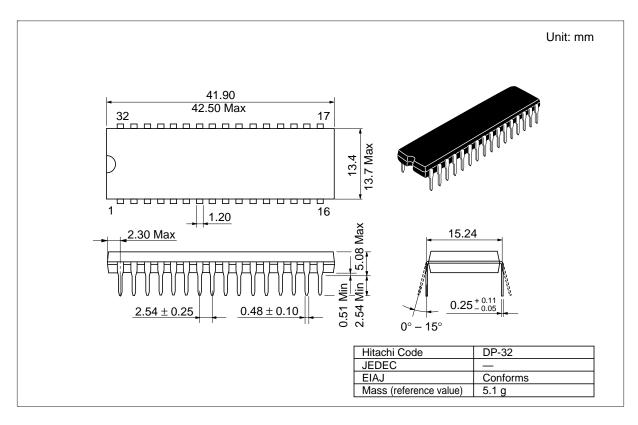
5. t_{RC} = read cycle time.

Low V_{CC} Data Retention Timing Waveform (\overline{CS} Controlled)



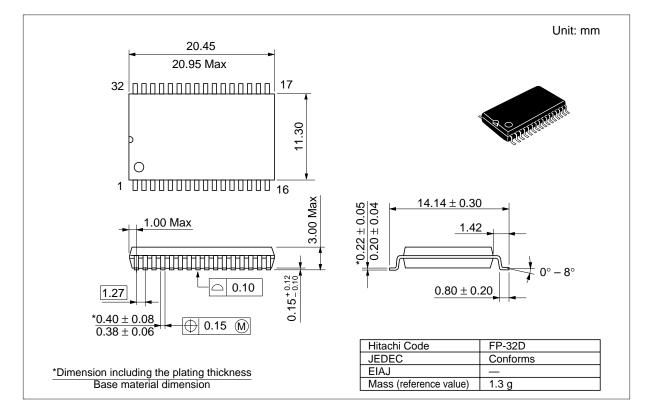
Package Dimensions

HM628512CLP Series (DP-32)



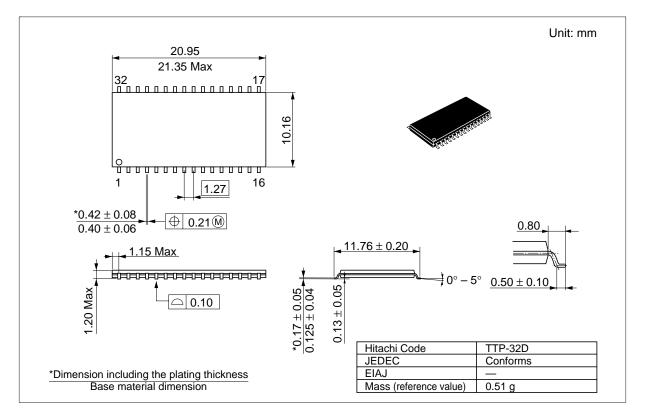
Package Dimensions (cont.)

HM628512CLFP Series (FP-32D)



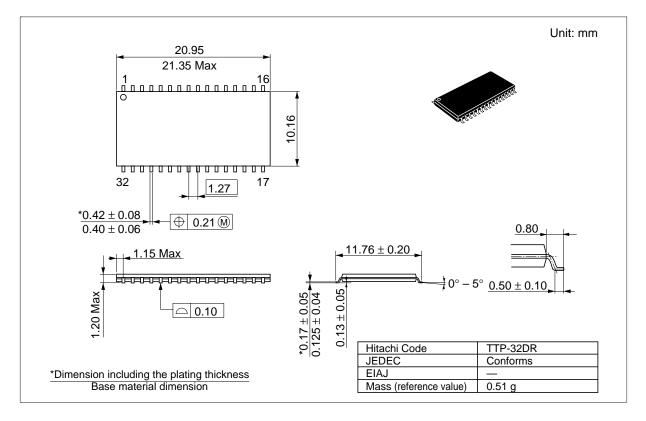
Package Dimensions (cont.)

HM628512CLTT Series (TTP-32D)



Package Dimensions (cont.)

HM628512CLRR Series (TTP-32DR)



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